



Material declaration form

| General Information | | | |
|---------------------|---------------------------|----------------|-----|
| IPC | 1752 | Version | 2 |
| Form type* | Distribute | | |
| Sectionals* | Material information | Subsectionals* | A-D |
| | Manufacturing information | | |

| Supplier Information | | | |
|----------------------------|---|-----------------------|-----------------------------------|
| Company name* | STMicroelectronics | Response Date* | 2025-01-23 |
| Contact name* | Refer to Supplier Comment section | | Refer to Supplier Comment section |
| Contact phone* | Refer to Supplier Comment section | Contact email* | Refer to Supplier Comment section |
| Authorized representative* | Antonella Lanzafame | Representative title | APMSMaterial Declaration champion |
| Representative phone* | Refer to Supplier Comment section | Representative email* | Refer to Supplier Comment section |
| Supplier comment | Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html | | |

Uncertainty statement

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Legal statement

| | | | |
|----------------------|------|--------------------|----------|
| Supplier acceptance* | true | Legal declaration* | Standard |
|----------------------|------|--------------------|----------|

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

| Product | | | | |
|------------------|------------------|-----------------|--------------------|------------------|
| Mfr item number | Mfr item name | Version | Manufacturing site | date |
| SCTHCT250N12G3AG | TTM8*BRJNL12 | A | SH1A | 2025-01-23 |
| | Amount | Unit of measure | Unit type | ST ECOPACK grade |
| | 8050 | mg | Each | ECOPACK® 2 |
| Identity | Authority | | | |
| Comment | 0 | | | |

| Manufacturing information | | | |
|---------------------------|----------------------------------|-------------------------|---------|
| J-STD-020 MSL rating | Classification temperature | Number of reflow cycles | |
| 3 | 220 | 3 | |
| Bulk solder termination | Terminal plating | Terminal base alloy | Comment |
| Not Applicable | Nickel/Palladium/Gold (Ni/Pd/Au) | Copper Alloy | 0 |

| | | | |
|--------------------|---------------|---------------------|-------|
| Package designator | Package size | Number of instances | Shape |
| SMO-THO | 18.8x28 | 4 | Mixed |
| Comment | | | |
| Comment | B0M8 STPAK HC | | |

| QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015 | | Response |
|--|--|----------|
| 1 - Product(s) meets EU RoHS requirement without any exemptions | | false |
| 2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply) | | false |
| 3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s) | | true |
| 4 - Product(s) does not meet EU RoHS requirements and is not under exemptions | | false |
| Exemption Id. | Description | |
| 7a | Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead) | |

| QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020 | | Response |
|---|--|----------|
| 1 - Product(s) meets EU ELV requirements without any exemptions | | true |
| 2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s) | | false |
| Exemption Id. | Description | |
| 8(e) | 8(e) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) | |

| QueryList : California Prop65 list, dated 17th Nov 2023 | | | | Response |
|--|------------------------|-------------|----------------|----------|
| 1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen | | | | false |
| 2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen | | | | true |
| Substance | amount in product (mg) | Application | ppm in product | |
| Nickel | 0.866 | alloy | 108 | |
| Lead | 8.078 | solder | 1003 | |

| QueryList :Customer | | Response |
|---------------------|--|----------|
| QUERY | | Response |

| QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014 | | | | | Response |
|---|--------------|--------------|-----------------------------|------------|----------|
| QUERY | | | | | Response |
| 1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products | | | | | true |
| 2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products | | | | | false |
| Hazardous substance | | | | | |
| Lead (Pb) | Cadmium (Cd) | Mercury (Hg) | Hexavalent Chromium (Cr VI) | PBB & PBDE | |
| X | O | O | O | O | |
| Soft solder | | | | | |
| Homogeneous Material(s) containing Lead | | | | | |

| QueryList : REACH-7th November 2024 | | | | | Response |
|---|-------------------------|--|--|--------------------------------------|----------|
| 1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH | | | | | false |
| CategoryLevel_Name | CategoryLevel_Threshold | amount in product (mg) | Application | ppm in product | |
| Lead (Pb) | 1000 ppm | 8.08 | Soft solder | 1003 | |
| 2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH | | | | | false |
| CategoryLevel_Name | CategoryLevel_Threshold | Amount in embedded article / Homogeneous material (mg) | Application - article / Homogeneous material | ppm in article /Homogeneous material | |
| Lead dinitrate | 1000 ppm | 8.078 | Soft solder | 954959 | |



| QueryList : Responsible metals sourcing | Response |
|---|-------------|
| The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten. | true |
| The following metals are present is the component : | Tin, |

| QueryList : Korea Chemical Control Act_ 27 Dec 2017 update | Response |
|--|----------|
| The Product does contain at least one of the substances listed in Chemical Control Act | false |

| QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020 | Response |
|--|----------|
| The product contains adhesives identified under GB 33372 | false |

| QueryList:Stockholm Convention Persistent Organic Pollutants (POP) | Response |
|--|----------|
| Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants | true |

| QueryList: EU Ship Recycling Regulation No. 1257/2013 | Response |
|---|----------|
| Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive | True |
| The material present in the product is: | Lead |

| PFAS/PTFE Declaration | Response |
|--|----------|
| The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride | False |

| BPA Declaration | Response |
|---|----------|
| Product does not contain Bisphenol A (Isopropylidenediphenol) | True |

| Montreal Protocol | Response |
|--|----------|
| Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009 | True |

| Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h) | Response |
|---|----------|
| Product does not contain Phenol, isopropylated, phosphate (3:1) | True |



| Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document | | | | | | Mfr Item Name | TTM8*BRJNL12 | | 8050.0000 | | 5999999.0 | 999998.0 |
|--|---------------------------------|----------|-----------------|---------------|--------------------|----------------------|--------------|--------------------------------|-----------|-----------------|---|--------------------------------|
| Homogeneous material | Material group | Mass | Unit of measure | Level | Substance category | Substance | CAS | Exempt | Mass | Unit of measure | Concentration in homogeneous material (ppm) | Concentration in product (ppm) |
| Die | M-011 Other inorganic materials | 14.790 | mg | supplier | die | Silicon(Si) | 7440-21-3 | | 0.060 | mg | 4057 | 7 |
| | M-011 Other inorganic materials | | | California 65 | die | Silicium carbide | 409-21-2 | | 13.864 | mg | 937390 | 1722 |
| | | | | supplier | metallisation | Aluminium(Al) | 7429-90-5 | | 0.253 | mg | 17106 | 31 |
| | | | | supplier | metallisation | Copper(Cu) | 7440-50-8 | | 0.034 | mg | 2299 | 4 |
| | | | | supplier | metallisation | Nickel(Ni) | 7440-02-0 | | 0.217 | mg | 14672 | 27 |
| | | | | supplier | metallisation | Silver(Ag) | 7440-22-4 | | 0.222 | mg | 15010 | 28 |
| | | | | supplier | metallisation | Titanium(Ti) | 7440-32-6 | | 0.027 | mg | 1826 | 3 |
| | | | | supplier | metallisation | Vanadium(V) | 7440-62-2 | | 0.007 | mg | 473 | 1 |
| | | | | supplier | Passivation | Silicon nitride(SiN) | 12033-89-5 | | 0.040 | mg | 2705 | 5 |
| | | | | supplier | passivation | Silicon oxide | 7631-86-9 | | 0.066 | mg | 4462 | 8 |
| Leadframe | M-004 Copper and its alloys | 1890.260 | mg | supplier | alloy | Copper(Cu) | 7440-50-8 | | 1885.585 | mg | 997527 | 234234 |
| | | | | supplier | alloy | Iron phosphide | 26508-33-8 | | 1.586 | mg | 839 | 197 |
| | | | | supplier | alloy | Iron(Fe) | 7439-89-6 | | 0.869 | mg | 460 | 108 |
| | | | | supplier | metallization | Silver(Ag) | 7440-22-4 | | 2.220 | mg | 1174 | 276 |
| Soft solder | Solder | 8.459 | mg | SVHC | solder | Lead(Pb) | 7439-92-1 | 7a-Lead in high melting temper | 8.078 | mg | 954959 | 1003 |
| | | | | supplier | solder | Tin(Sn) | 7440-31-5 | | 0.169 | mg | 19979 | 21 |
| | | | | supplier | solder | Silver(Ag) | 7440-22-4 | | 0.212 | mg | 25062 | 26 |
| Encapsulation | M-011 Other inorganic materials | 1994.836 | mg | supplier | mold compound | Silica vitreous | 60676-86-0 | | 1496.126 | mg | 749999 | 185854 |
| | | | | supplier | mold compound | Silica | 7631-86-9 | | 199.484 | mg | 100000 | 24781 |
| | | | | supplier | mold compound | Epoxy resin | proprietary | | 199.484 | mg | 100000 | 24781 |
| | | | | supplier | mold compound | Phenol resin | proprietary | | 99.742 | mg | 50000 | 12390 |
| solder paste | Solder | 8.655 | mg | supplier | solder | Silver(Ag) | 7440-22-4 | | 6.924 | mg | 800000 | 860 |
| | | | | supplier | solder | Nickel(Ni) | 7440-02-0 | | 0.649 | mg | 74986 | 81 |
| | | | | supplier | solder | other | proprietary | | 1.082 | mg | 125014 | 134 |
| Ceramic package base | | 4133.000 | mg | supplier | ceramic | Ceramic Si3N4 | 12033-89-5 | | 312.992 | mg | 75730 | 38881 |
| | | | | supplier | 0 | Silver | 7440-22-4 | | 3.017 | mg | 730 | 375 |
| | | | | supplier | 0 | Copper | 7440-50-8 | | 3754.996 | mg | 908540 | 466459 |
| | | | | supplier | 0 | Brazing paste | Proprietary | | 61.995 | mg | 15000 | 7701 |